

THICK FILM MILLIMETER WAVE TRANSCEIVER MODULE

Abstract of the Disclosure

A thick film millimeter wave transceiver module includes a base plate and a multi-layer substrate board having a plurality of layers of low temperature transfer tape received on the base plate. The different layers can vary. They can include a DC signals layer having signal tracks in connection; a ground layer having ground connections; a device layer having capacitors and resistors embedded therein; and a top layer having cut-outs for receiving MMIC chips therein. A solder preform layer is located between the device layer and the top layer for securing any MMIC chips. A channelization plate is received over the multi-layer substrate board and a channel is formed to receive MMIC chips and provide isolation between transmit and receive signals.

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